

# **Notice of References Cited**

Application/Control No.

09/483,881

Applicant(s)/Patent Under  
Reexamination  
AHN ET AL.

Examiner

Ha T. Nguyen

Art Unit

2812

Page 1 of 1

## **U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5034799 /	07-1991	Tomita et al.	438
	B	US-6372622 /	04-2002	Tan et al.	438
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

## **FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

## **NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)				
	U	Bernier et al., "Laser processing of palladium for selective electroless copper plating", SPIE vol.2045, 1994, pp.330-337				
	V					
	W					
	X					

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

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